

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4395	257/692-697.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/01/12 09:09
L2	751	L1 and (solder near (bump ball))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/01/12 09:11
L3	0	2 and (voltage near1 monitor)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/01/12 09:11
L4	9497	(voltage near1 monitor)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/01/12 09:12
L5	2365	4 and (substrate pcb ((wiring circuit) near1 board))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/01/12 09:23
L6	1614	5 and (chip die ic (integrated adj circuit))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/01/12 09:24
L7	782	6 and lead	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/01/12 09:13
L8	124	7 and (bump ball)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/01/12 09:13
L9	81	4 with (substrate pcb ((wiring circuit) near1 board))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/01/12 09:23
L10	46	9 and (chip die ic (integrated adj circuit))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/01/12 09:24